



Capability

Item	Description	Process Capability	General
Laminate	Type	Rogers/Taconic/Arlon/Isola/Nelco/CHUKOH/FR-4/F4B/TP-2/High TG...	
	Thickness	0.1-12mm	
Process Capability	Layer	2-36 layers radio frequency PCB, Hybrid PCB, Multilayer HDI PCB	
	Surface Finish	ENIG/Gold Plating/Immersion Silver/Silver Plating/HASL/Gold finger/OSP/Nickel-palladium Gold/Resin plugging/Countersinking/ENIG+Hard Gold Plating/ImNi+ImTin/ENIG+OSP	
Copper Foil Thickness	Completed Copper Thickness	0.5oz-5oz	1oz-3oz
Size	Max Panel Size	480*800mm	600*600mm
Drilling	Drilling Diameter	≥0.1mm	≥0.2mm
	Aperture Tolerance	±0.05mm	±0.075-±0.08mm
	Hole Position Tolerance	±0.05mm	±0.075mm
Inner Layer	Inner Core Thickness	0.1-4.0mm	0.2-2.0mm
	Trace/Space	2.5mil/3mil	3mil/4mil
	Registration Precision	2mil	3mil
Size	Plate Thickness Tolerance	±0.1	±10%
	Registration	≤0.05mm	≤0.1mm
Electroless Plating Copper	Hole Wall Copper Thickness	20um-50um	≥20um
Profiling	Profile Type	Routing/Punching/V-CUT/Beveled Edges Laser Cutting	
Out Layer	Trace/Space	2.5mil/3mil	3mil/4mil
Etching	Tolerance	±0.01mm	±20%
Processing	BGA	≥8mil	≥12mil
	IC	≥3mil	≥6mil
	Aspect Ratio	14:01	10:01
	Board Thickness	0.1-10.0mm	0.2-4.0mm
Chemical Gold Plating/Electronic Plating	Nickel Thickness	≥120u	
	Gold Thickness	1-5u	
Solder Mask	Color	Green/Blue/Black/Red/White/Yellow	
	Thickness	15-35um	
	Solder Mask Bridge	≥3mil	≥5mil
	Plug Hole Diameter	0.15-0.6mm	0.3-0.4mm
Legend	Color	Green/Blue/Black/Red/White/Yellow	
	Trace Width/Space	6mil/6mil	
Impedance	Impedance Tolerance	±10%	
Quality Control	Single and double Sided printed boards with plated-through holes technique standard GB4588.2-88, Design and Use of Printed Boards IPC-A-600G IPC-6015		